

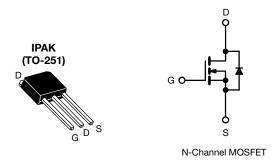
Vishay Siliconix

COMPLIANT

HALOGEN FREE

# **D Series Power MOSFET**

PRODUCT SUMMARY					
V <sub>DS</sub> (V) at T <sub>J</sub> max.	550				
R <sub>DS(on)</sub> max. (Ω) at 25 °C	V <sub>GS</sub> = 10 V	3.2			
Q <sub>g</sub> max. (nC)	12				
Q <sub>gs</sub> (nC)	2				
Q <sub>gd</sub> (nC)	3				
Configuration	Single				



#### **FEATURES**

- Optimal design
  - Low area specific on-resistance
  - Low input capacitance (Ciss)
  - Reduced capacitive switching losses
  - High body diode ruggedness
  - Avalanche energy rated (UIS)
- · Optimal efficiency and operation
  - Low cost
  - Simple gate drive circuitry
  - Low figure-of-merit (FOM): Ron x Qa
  - Fast switching
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912"><u>www.vishav.com/doc?99912</u></a>

### **APPLICATIONS**

- Consumer electronics
  - -Displays (LCD or plasma TV)
- Server and telecom power supplies
  - SMPS
- Industrial
  - Welding
  - Induction heating
  - Motor drives
- · Battery chargers

ORDERING INFORMATION				
Package	IPAK (TO-251)			
Lead (Pb)-free	SiHU3N50D-E3			
Lead (Pb)-free and Halogen-free	SiHU3N50D-GE3			

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V <sub>DS</sub>	500		
Gate-Source Voltage			.,	± 30	V	
Gate-Source Voltage AC (f > 1 Hz)			$V_{GS}$	30		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	$V_{GS}$ at 10 V $\frac{T_C}{T_C} = \frac{T_C}{T_C}$	$T_{\rm C} = 25  ^{\circ}{\rm C}$ $T_{\rm C} = 100  ^{\circ}{\rm C}$		3.0		
		T <sub>C</sub> = 100 °C	I <sub>D</sub>	1.9	А	
Pulsed Drain Current <sup>a</sup>			I <sub>DM</sub>	5.5		
Linear Derating Factor				0.56	W/°C	
Single Pulse Avalanche Energy b			E <sub>AS</sub>	10.4	mJ	
Maximum Power Dissipation			$P_{D}$	69	W	
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-Source Voltage Slope	T <sub>J</sub> = 12	5 °C	dV/dt	24	V/ns	
Reverse Diode dV/dt d			uv/ut	0.22	) v/ns	
Soldering Recommendations (Peak Temperature) c for 10 s			300	°C		

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b.  $V_{DD}$  = 50 V, starting  $T_J$  = 25 °C, L = 2.3 mH,  $R_g$  = 25  $\Omega$ ,  $I_{AS}$  = 3 Å.
- c. 1.6 mm from case.
- d.  $I_{SD} \le I_D$ , starting  $T_J = 25$  °C.



# Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	62	°C/W	
Maximum Junction-to-Case (Drain)	$R_{thJC}$	-	1.8	C/VV	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static						•	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		500	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I <sub>D</sub> = 250 μA	-	0.56	-	V/°C
Gate-Source Threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	· V <sub>GS</sub> , I <sub>D</sub> = 250 μA	3	-	5	V
Gate-Source Leakage	I <sub>GSS</sub>	,	V <sub>GS</sub> = ± 30 V		-	± 100	nA
Zava Cata Valtaga Dvain Coverent		V <sub>DS</sub> =	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V		-	1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 400 V	', V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	10	μA
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 2.5 A	-	2.6	3.2	Ω
Forward Transconductance a	9 <sub>fs</sub>	V <sub>DS</sub>	= 8 V, I <sub>D</sub> = 1.5 A	-	1	-	S
Dynamic							
Input Capacitance	C <sub>iss</sub>		$V_{GS} = 0 V$ ,	-	175	-	
Output Capacitance	C <sub>oss</sub>	1	V <sub>DS</sub> = 100 V,	-	21	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		f = 1 MHz	-	5	-	
Effective Output Capacitance, Energy Related <sup>b</sup>	C <sub>o(er)</sub>	V 0VV 400V V 0V		-	21	-	pF -
Effective Output Capacitance, Time Related <sup>c</sup>	C <sub>o(tr)</sub>	$V_{DS} = 0$	$V_{DS} = 0 \text{ V to } 400 \text{ V}, V_{GS} = 0 \text{ V}$		26	-	
Total Gate Charge	Qg			-	6	12	
Gate-Source Charge	Q <sub>gs</sub>	$V_{GS} = 10 \text{ V}$ $I_D = 1.5 \text{ A}, V_{DS} = 400 \text{ V}$		-	2	-	nC
Gate-Drain Charge	Q <sub>gd</sub>			-	3	-	
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 400 V, I <sub>D</sub> = 1.5 A		-	12	24	ns
Rise Time	t <sub>r</sub>			-	9	18	
Turn-Off Delay Time	t <sub>d(off)</sub>	$R_g =$	$R_g = 9.1 \Omega, V_{GS} = 10 V$		11	22	
Fall Time	t <sub>f</sub>				13	26	
Gate Input Resistance	$R_g$	f = 1 MHz, open drain		-	3.3	-	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	3	
Pulsed Diode Forward Current	I <sub>SM</sub>			-	-	12	- A
Diode Forward Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 1.5 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = I <sub>S</sub> = 1.5 A, dl/dt = 100 A/ $\mu$ s, V <sub>R</sub> = 20 V		-	293	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>			-	0.74	-	μC
Reverse Recovery Current	I <sub>RRM</sub>			_	5	-	A

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ . c.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

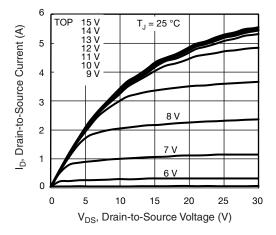


Fig. 1 - Typical Output Characteristics

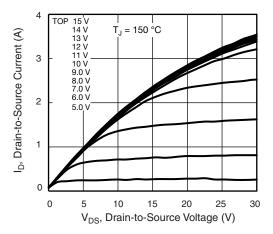


Fig. 2 - Typical Output Characteristics

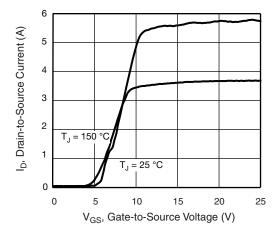


Fig. 3 - Typical Transfer Characteristics

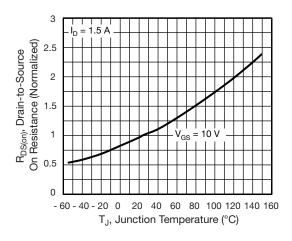


Fig. 4 - Normalized On-Resistance vs. Temperature

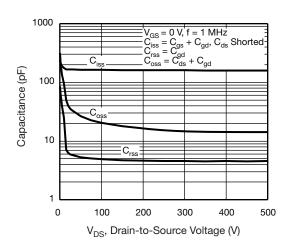


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

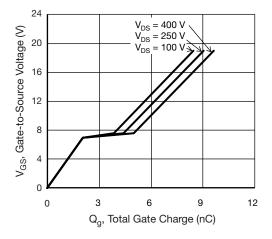


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



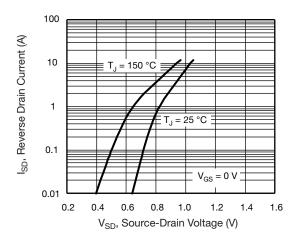


Fig. 7 - Typical Source-Drain Diode Forward Voltage

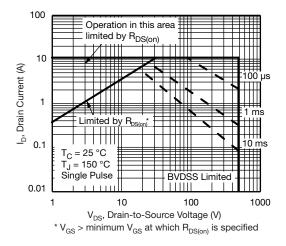


Fig. 8 - Maximum Safe Operating Area

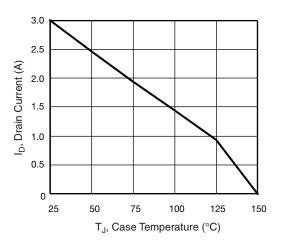


Fig. 9 - Maximum Drain Current vs. Case Temperature

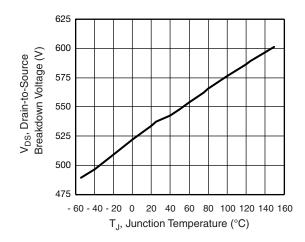


Fig. 10 - Typical Drain-to-Source Voltage vs. Temperature

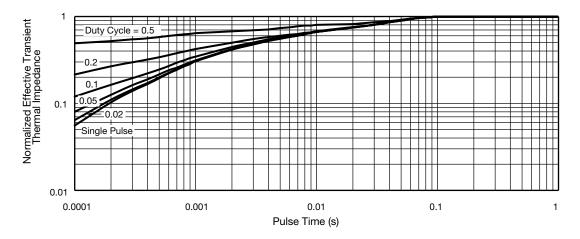


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case



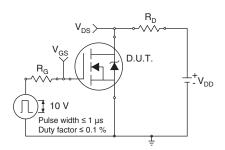


Fig. 12 - Switching Time Test Circuit

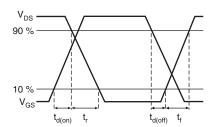


Fig. 13 - Switching Time Waveforms

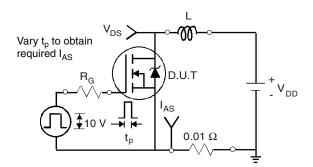


Fig. 14 - Unclamped Inductive Test Circuit

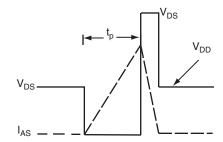


Fig. 15 - Unclamped Inductive Waveforms

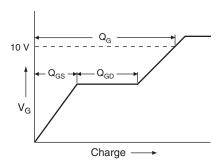


Fig. 16 - Basic Gate Charge Waveform

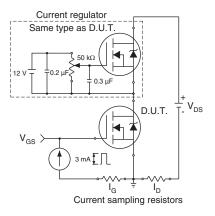
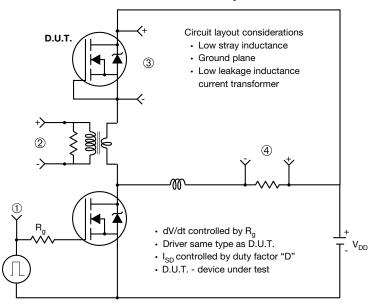


Fig. 17 - Gate Charge Test Circuit



### Peak Diode Recovery dV/dt Test Circuit



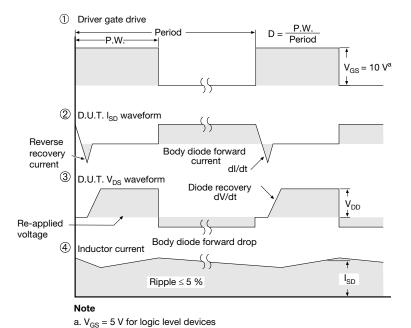
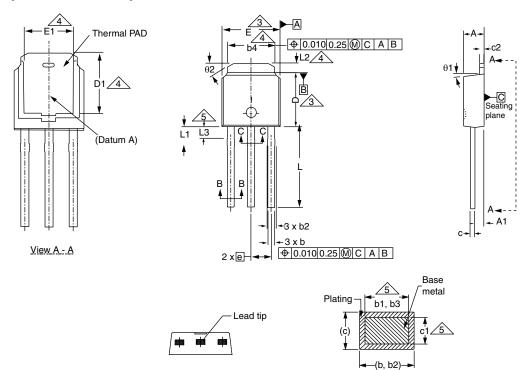


Fig. 18 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?91493">www.vishay.com/ppg?91493</a>.



## **TO-251AA (HIGH VOLTAGE)**



**MILLIMETERS INCHES** DIM. MIN. MAX. MIN. MAX. Α 2.18 2.39 0.086 0.094 Α1 0.89 1.14 0.035 0.045 b 0.64 0.89 0.025 0.035 b1 0.65 0.79 0.026 0.031 0.76 1.14 0.030 0.045 b2 b3 0.76 1.04 0.030 0.041 b4 4.95 5.46 0.195 0.215 0.61 0.018 0.024 0.46 С с1 0.41 0.56 0.016 0.022 c2 0.46 0.86 0.018 0.034 5.97 6.22 0.235 0.245

	MILLIN	IETERS	INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
D1	5.21	-	0.205	-	
Е	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
е	2.29	BSC	2.29 BSC		
L	8.89	9.65	0.350	0.380	
L1	1.91	2.29	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.14	1.52	0.045	0.060	
θ1	0'	15'	0'	15'	
θ2	25'	35'	25'	35'	

Section B - B and C - C

ECN: S-82111-Rev. A, 15-Sep-08

DWG: 5968

- 1. Dimensioning and tolerancing per ASME Y14.5M-1994.
- 2. Dimension are shown in inches and millimeters.
- 3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.13 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body.
- 4. Thermal pad contour optional with dimensions b4, L2, E1 and D1.
- 5. Lead dimension uncontrolled in L3.
- 6. Dimension b1, b3 and c1 apply to base metal only.
- 7. Outline conforms to JEDEC outline TO-251AA.

Document Number: 91362 Revision: 15-Sep-08



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Revision: 13-Jun-16 1 Document Number: 91000

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